



Singapore`s TECH Semiconductor Purchases Applied Materials` High-Throughput Producer CVD Systems

September 13, 1999

Business Editors, High-Tech Writers

SANTA CLARA, Calif.--(BUSINESS WIRE)--September 13, 1999--

Producer Selected for Rapid Conversion of TECH's Fabs,
Providing Highest Productivity per System Area

TECH Semiconductor Pte. Ltd. of Singapore, a joint manufacturing venture of Micron Technology, Inc., the Economic Development Board of Singapore, Canon Inc. and Hewlett-Packard Co., has purchased multiple Producer(TM) CVD (chemical vapor deposition) systems from Applied Materials, Inc. Delivery of the systems began this year to TECH Semiconductor's facility in Woodlands, located in northern Singapore.

Lee Kok Choy, vice president of operations for TECH Semiconductor, said, "The Producer system's exceptional output and technical performance provides a large productivity benefit in a compact package. These features are essential in converting our fabs to manufacture next-generation DRAM chips. Since the Producer uses the same processes that have already been proven on our other Applied Materials' CVD systems, we can ramp the Producer systems quickly into production with minimal requalification."

"Cost-competitive DRAM production requires high system productivity and low cost of ownership. TECH Semiconductor's choice of the Producer system validates its effectiveness in addressing very advanced technology requirements with high throughput," said Dr. Farhad Moghadam, vice president and general manager of Applied Materials' Dielectric Deposition Products Division. "We are delighted to be working with TECH Semiconductor to help commercialize their latest generation of DRAM products."

Introduced in 1998, the Producer has a unique platform architecture that features a central transfer chamber mounted with up to three Twin Chamber(TM) CVD process modules. Wafers are transferred in pairs to each Twin Chamber module, allowing up to six wafers to be processed simultaneously. Producer can achieve throughputs of more than 110 wafers per hour and process more than 10,000 wafers between wet cleans (MWBC) per Twin Chamber. An efficient Remote Clean(TM) chamber cleaning technology extends hardware and consumables lifetime, lowers particles and emits virtually no global warming gases. Applied Materials' Producer system is capable of depositing a number of dielectric films using silane, TEOS and SACVD(TM) (sub-atmospheric CVD) TEOS/ozone process chemistries.

According to Dataquest, a market research company, the market for equipment used to deposit dielectric CVD films totaled \$1.4 billion in 1998 and is projected to reach \$3.1 billion by 2003.

Applied Materials, Inc. is a Fortune 500 global growth company and the world's largest supplier of wafer fabrication systems and services to the global semiconductor industry. Applied Materials is traded on the Nasdaq National Market System under the symbol "AMAT." Applied Materials' web site is www.appliedmaterials.com.

--30--RYG/se*

CONTACT: Applied Materials, Inc.
Betty Newboe, 408/563-0647 (editorial/media)
Carolyn Schwartz, 408/748-5227 (financial community)

KEYWORD: CALIFORNIA INTERNATIONAL ASIA PACIFIC
INDUSTRY KEYWORD: COMPUTERS/ELECTRONICS COMED PRODUCT